

What I claim is:

1. A circuit board for a semiconductor device, comprising:

a plurality of pads on which the semiconductor device is to be mounted, said pads being formed on the circuit board;

5 a plurality of terminals formed on a side edge of the circuit board;

a resist film covering an area on the circuit board between said pads and said terminals; and

a barrier formed between said pads and said terminals.

10 2. A circuit board for a semiconductor device as claimed in claim 1, wherein said barrier is a wall disposed along said terminals, said wall being formed on said resist film.

3. A circuit board for a semiconductor device as claimed in claim 1, wherein said
15 barrier includes a plurality of walls disposed along said terminals, said walls being formed on said resist film.

4. A circuit board for a semiconductor device as claimed in claim 3, wherein said
20 walls are parallel to each other, and a height of each said wall is not less than a diameter of a solder ball which is formed when the semiconductor device is mounted on the pads.

5. A circuit board for a semiconductor device as claimed in claim 1, wherein said barrier is an elongated trench disposed along said terminals, said trench being formed in said resist film

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6. A circuit board for a semiconductor device as claimed in claim 1, wherein said barrier includes a plurality of trench disposed along said terminals, said trenches being formed in said resist film.

10 7. A circuit board for a semiconductor device as claimed in claim 6, wherein said trenches are parallel to each other.

8. A circuit board for a semiconductor device as claimed in claim 1, wherein said barrier includes an elongated trench disposed along said terminals, said trench being
15 formed in said resist film, said barrier further including a wall along the terminals, the wall being formed on said resist film.

9. A circuit board for a semiconductor device as claimed in claim 8, wherein said wall is disposed between said trench and said terminals

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10. A circuit board for a semiconductor device as claimed in claim 1, wherein said barrier includes an elongated trench disposed along said terminals, said trench being

formed in said resist film, said barrier further including an elongated metal layer which is formed in said trench.

11. A circuit board for a semiconductor device as claimed in claim 10, wherein said
5 metal layer has a width not less than a diameter of a solder ball which is formed when the semiconductor device is mounted on the pads.

12. A circuit board for a semiconductor device as claimed in claim 11, wherein said metal layer is formed of copper which is plated with flash gold.

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